

Surface Mount Switching Multi-Chip Diode Array

(Pb) Lead(Pb)-Free

Features:

- * For General Purpose Switching Applications
- * Fast Switching Speed
- * High Conductance
- * Easily Connected As Full Wave Bridge

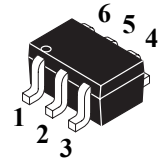
Mechanical Data:

- * Case : SOT-363
- * Case Material : Molded Plastic. UL Flammability Classification Rating 94V-0
- * Moisture Sensitivity : Level 1 per J-STD-020C
- * Terminals : Solderable per MIL-STD-202, Method 208
- * Polarity : See Diagram
- * Weight : 0.006 grams(appro)

MULTI-CHIP DIODES

150m AMPERES

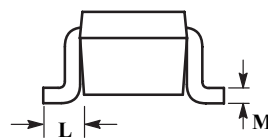
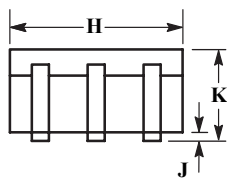
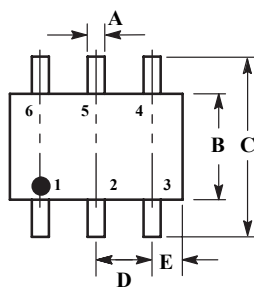
75 VOLTS



SOT-363

SOT-363 Outline Dimensions

Unit:mm



SOT-363		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 REF	
E	0.30	0.40
H	1.80	2.20
J	-	0.10
K	0.80	1.10
L	0.25	0.40
M	0.10	0.25

Maximum Ratings (T_A=25°C Unless otherwise noted)

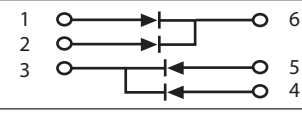
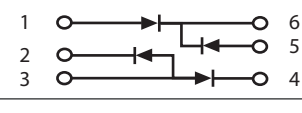
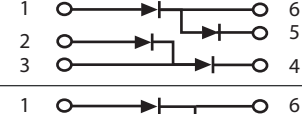
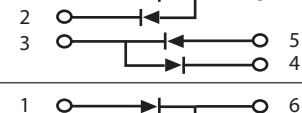
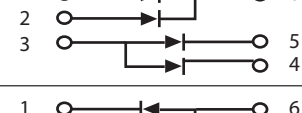
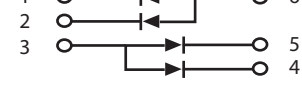
Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RM} V _R	75	V
RMS Reverse Voltage	V _{R(RSM)}	53	V
Average Rectified Output Current ^(1,3)	I _O	150	mA
Non-Repetitive Forward Current @t=1.0μs @t=1.0s	I _{FSM}	2.0 1.0	A
Power Dissipation ^(1,3)	P _D	200	mW
Thermal Resistance, Junction to Ambient Air ^(1,3)	R _{θJA}	625	°C/W
Junction & Storage Temperature Range	T _j ,T _{stg}	-65 to +150	°C

Electrical Characteristics (T_A=25°C Unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage ⁽²⁾ I _R =2.5μA	V _{(BR)R}	75	-	-	A
Reverse Current ⁽²⁾ V _R =75V V _R =20V	I _R	-	-	2.5 25	μA nA
Forward Voltage ⁽²⁾ I _F =1mA I _F =10mA I _F =50mA I _F =150mA	V _F	-	-	715 855 1000 1250	mA
Total Capacitance (V _R =0V, f=1.0MHz)	C _D	-	-	2.0	pF
Reverse Recover Time I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω	T _{rr}	-	-	4.0	nS

Notes: 1. Device mounted on FR-4 PC board with recommended pad layout.
 2. Short duration test pulse used to minimize self-heating effect.
 3. One or more diodes loaded.

Device Marking

Item	Marking	Equivalent Circuit diagram
BAV70DW	KJA	
BAV756DW	KCA	
BAV99BRW	KGJ	
BAV99DW	KJG	
BAW567DW	KAC	
BAW56DW	KJC	

Typical Characteristics

